

<Full SiC Power Modules>

FMF400BX-24B

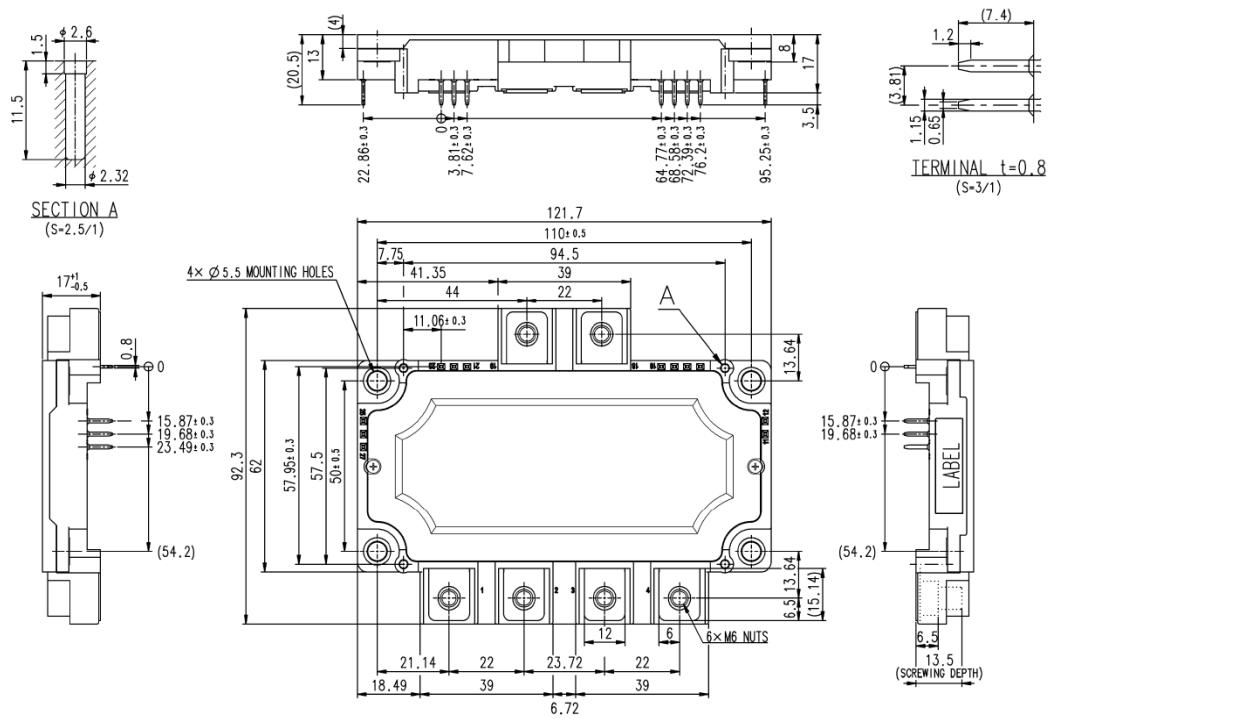
**HIGH POWER SWITCHING USE
INSULATED TYPE**


fourpack

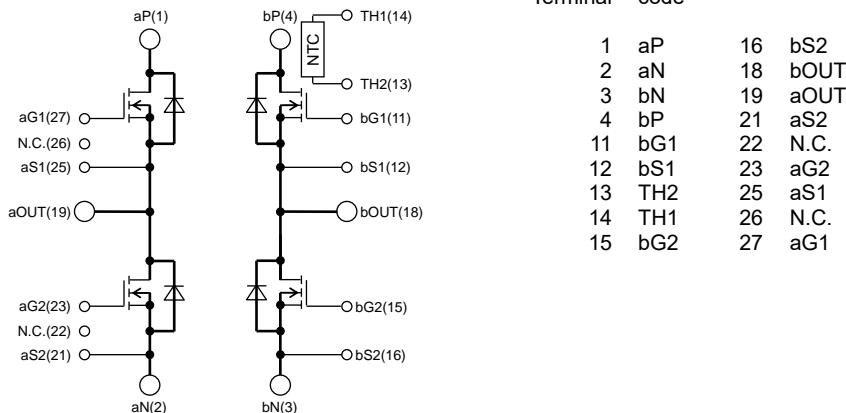
Drain current I_D 400 A
 Drain-Source voltage V_{DSX} 1200 V
 Maximum junction temperature $T_{vj\max}$ 175 °C
 •Silicon Carbide MOSFET + Silicon Carbide Schottky Barrier Diode
 •Flat base Type
 •Copper base plate
 •RoHS Directive compliant
 •Recognized under UL1557, File E323585

APPLICATION

AC Motor Control, Motion/Servo Control, Power supply, etc.

OUTLINE DRAWING & INTERNAL CONNECTION

INTERNAL CONNECTION

Terminal code



FMF400BX-24BHIGH POWER SWITCHING USE
INSULATED TYPE**MAXIMUM RATINGS (T_{vj} = 25 °C, unless otherwise specified)**

Symbol	Item	Conditions	Rating	Unit
V _{DSX}	Drain-source voltage	V _{GS} =-15 V	1200	V
V _{GSS}	Gate-source voltage	D-S short-circuited	±20	V
I _D	Drain current	DC, T _C =60°C (Note.2)	400	A
I _{DRM}		Pulse, Repetitive (Note.3), T _{vj} =150°C (Note.4)	800	
P _{tot}	Total power dissipation	T _C =25 °C (Note. 2)	1560	W
I _S (Note.1)	Source current	DC	400	A
I _{SRM} (Note.1)		Pulse, Repetitive (Note.3), T _{vj} =150°C	800	
V _{isol}	Isolation voltage	Terminals to base plate, RMS, f=60 Hz, AC 1 min	5000	V
T _{vjmax}	Maximum junction temperature	Instantaneous event (overload) (Note.11)	175	°C
T _{vjop}	Operating junction temperature	Continuous operation (under switching) (Note.11)	-40~+150	°C
T _{cmax}	Maximum case temperature	(Note.2, 10)	125	°C
T _{stg}	Storage temperature	-	-40~+125	°C

ELECTRICAL CHARACTERISTICS (T_{vj}=25 °C, unless otherwise specified)

Symbol	Item	Conditions (note10)		Limits		Unit
			Min.	Typ.	Max.	
I _{DSX}	Drain-source cut-off current	V _{DS} =V _{DSX} , V _{GS} =-15 V	-	-	4	mA
		V _{DS} =800V, V _{GS} =-15 V	-	-	0.4	
V _{GS(th)}	Gate-source threshold voltage	I _D =113 mA, V _{DS} =10 V	1.8	2.5	3.2	V
I _{GSS}	Gate-source leakage current	V _{GS} =V _{GSS} , D-S short-circuited	-	-	0.5	µA
V _{DS(on)} (terminal)	Drain-source on-state voltage	I _D =400 A, V _{GS} =15V (Note.6)	T _{vj} =25 °C	-	1.65	2.30
			T _{vj} =125 °C	-	2.10	-
			T _{vj} =150 °C	-	2.20	-
V _{DS(on)} (chip)	Drain-source on-state voltage	I _D =400 A, V _{GS} =15V (Note.6)	T _{vj} =25 °C	-	1.35	-
			T _{vj} =125 °C	-	1.80	-
			T _{vj} =150 °C	-	1.90	-
r _{DS(on)} (chip)	Drain-source on-state resistance	I _D =400 A, V _{GS} =15V (Note.6)	T _{vj} =25 °C	-	3.4	-
			T _{vj} =125 °C	-	4.5	-
			T _{vj} =150 °C	-	4.8	-
C _{iss}	Input capacitance	V _{DS} =10 V, V _{GS} =0V	-	34	-	nF
C _{oss}	Output capacitance		-	24	-	
C _{rss}	Reverse transfer capacitance		-	1.7	-	
Q _G	Gate charge	V _{DD} =600 V, I _D =400 A, V _{GS} =0→15 V	-	975	-	nC
t _{d(on)}	Turn-on delay time	V _{DD} =600 V, I _D =400 A, V _{GS} =±15 V, T _{vj} =150°C, R _G =3.0Ω, L _{s_ext} =25nH, Inductive load, per pulse	-	120	-	ns
t _r	Rise time		-	80	-	
t _{d(off)}	Turn-off delay time		-	200	-	
t _f	Fall time		-	30	-	
E _{on}	Turn-on switching energy		-	16	-	mJ
E _{off}	Turn-off switching energy		-	7	-	
Q _C	Drain-source charge		-	2	-	µC
V _{SD} (Note.1) (terminal)	Source-drain voltage	I _S =400 A (Note.6) V _{GS} =-15 V	T _{vj} =25 °C	-	1.90	2.45
			T _{vj} =125 °C	-	2.70	-
			T _{vj} =150 °C	-	2.90	-
V _{SD} (Note.1) (chip)	Source-drain voltage	I _S =400 A (Note.6) V _{GS} =-15 V	T _{vj} =25 °C	-	1.60	-
			T _{vj} =125 °C	-	2.40	-
			T _{vj} =150 °C	-	2.60	-
R _{DD'+SS'}	Internal lead resistance	aP-aS1, bP-bS1, aOUT-aS2, bOUT-bS2 terminals, per switch	-	0.75	-	mΩ
L _s	Internal stray inductance	aP-aN, bP-bN	-	18	-	nH
r _g	Internal gate resistance	Per switch	-	1.75	-	Ω

Caution: Short-circuit capability is not designed.

FMF400BX-24BHIGH POWER SWITCHING USE
INSULATED TYPE**THERMAL RESISTANCE CHARACTERISTICS**

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
$R_{th(j-c)Q}$	Thermal resistance ^(Note. 2)	Junction to case, per inverter switch	-	-	96	K/kW
$R_{th(j-c)D}$		Junction to case, per inverter FWD	-	-	126	
$R_{th(c-s)}$	Contact thermal resistance ^(Note.2)	Case to heat sink, per 1 module, Thermal grease applied ^(Note.8, 11)	-	12	-	K/kW

NTC THERMISTOR PART

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R_{25}	Zero-power resistance	$T_c=25\text{ }^{\circ}\text{C}$ ^(Note.2)	4.85	5.00	5.15	k Ω
$\Delta R/R$	Deviation of resistance	$T_c=100\text{ }^{\circ}\text{C}$ ^(Note.2) , $R_{100}=493\text{ }\Omega$	-7.3	-	+7.8	%
$B_{(25/50)}$	B-constant	Approximate by equation ^(Note.7)	-	3375	-	K
P_{25}	Power dissipation	$T_c=25\text{ }^{\circ}\text{C}$ ^(Note.2)	-	-	10	mW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
M_t	Mounting torque	Main terminals	M 6 screw	3.5	4.0	4.5
M_s		Mounting to heat sink	M 5 screw	2.5	3.0	6.0
m	mass	-	-	423	-	g
d_a	Clearance	Terminal to terminal	10.0	-	-	mm
		Terminal to base plate	7.2	-	-	
d_s	Creepage distance	Terminal to terminal	14.4	-	-	mm
		Terminal to base plate	11.9	-	-	
e_c	Flatness of base plate	On the centerline X, Y ^(Note.5)	-100	-	+100	μm

*: This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU and (EU)2015/863.

Note1. Represent ratings and characteristics of the anti-parallel, source-drain free wheeling diode (FWD).

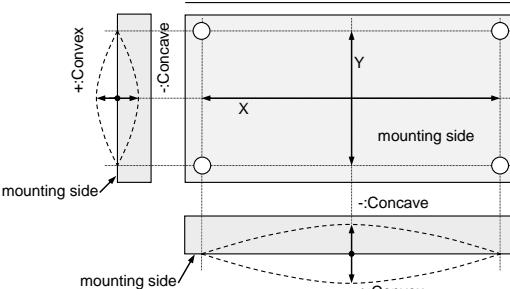
2. Case temperature (T_c) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink just under the chips.

Refer to the figure of chip location.

3. Pulse width and repetition rate should be such that the device junction temperature (T_{vj}) does not exceed $T_{vj\max}$ rating.

4. Junction temperature (T_{vj}) should not increase beyond $T_{vj\max}$ rating.

5. The base plate (mounting side) flatness measurement points (X, Y) are as follows of the following figure.



6. Pulse width and repetition rate should be such as to cause negligible temperature rise.

$$7. B_{(25/50)} = \ln\left(\frac{R_{25}}{R_{50}}\right) / \left(\frac{1}{T_{25}} - \frac{1}{T_{50}}\right)$$

R_{25} : resistance at absolute temperature T_{25} [K]; $T_{25}=25\text{ }^{\circ}\text{C}+273.15=298.15\text{ [K]}$

R_{50} : resistance at absolute temperature T_{50} [K]; $T_{50}=50\text{ }^{\circ}\text{C}+273.15=323.15\text{ [K]}$

8. Typical value is measured by using thermally conductive grease of $\lambda=0.9\text{ W/(m}\cdot\text{K)}$ / $D_{(C-S)}=100\mu\text{m}$.

9. Use the following screws when mounting the printed circuit board (PCB) on the standoffs.

" $\varphi 2.6\times 10$ or $\varphi 2.6\times 12$, B1 tapping screw"

The length of the screw depends on the thickness ($t1.6$) of the PCB.

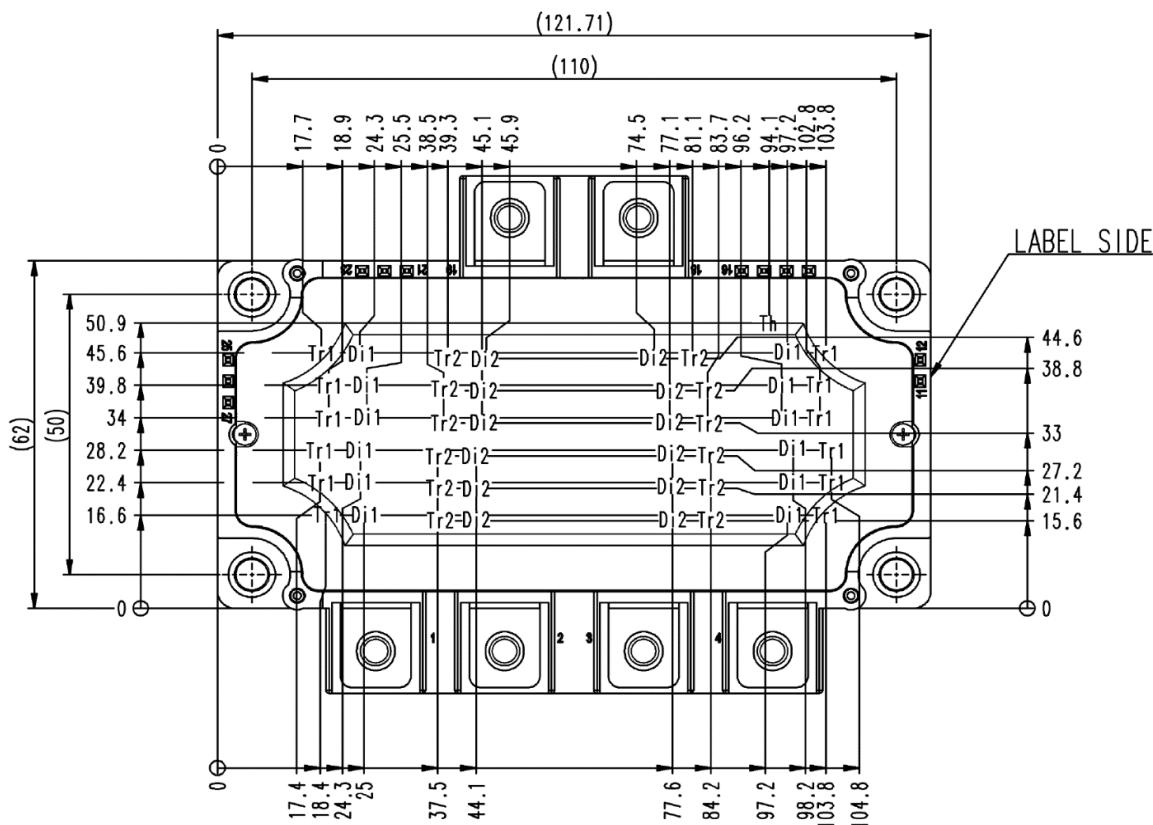
10. Per switch

11. Long term performance related to thermal conductive grease (including but not limited to aspects such as the increase of thermal resistance due to pumping out, etc.) should be verified under your specific application conditions. Each temperature condition ($T_{vj\max}$, $T_{vj\text{ op}}$, $T_c\max$) must be maintained below the maximum rated temperature throughout consideration of the temperature rise even for long term usage.

RECOMMENDED OPERATING CONDITIONS

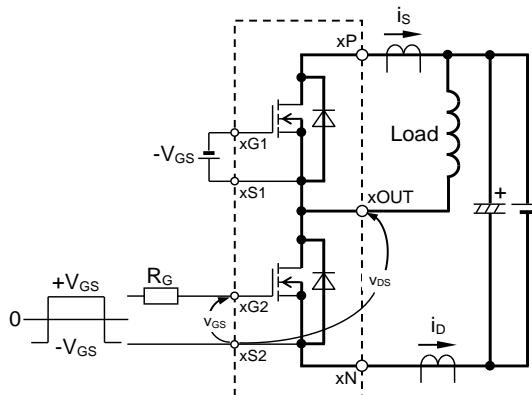
Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
V_{DD}	(DC) Supply voltage	Applied across aP -aN, bP-bN terminals	-	600	850	V
$V_{GS(+)}$	Gate-Source positive drive voltage	Applied across aG1-aS1, bG1-bS1, aG2-aS2, bG2-bS2 terminals	13.5	15.0	16.5	V
$V_{GS(-)}$	Gate-Source negative drive voltage	Applied across aG1-aS1, bG1-bS1, aG2-aS2, bG2-bS2 terminals	-16.5	-15.0	-7.0	V
R_G	External gate resistance (Note.12)	Per switch	3.0	-	15.0	Ω
f_c	Switching frequency	$V_{GS(+)}=15V, R_G=3.0\Omega$ $V_{DD}=600V, T_{vj}=150^\circ C$	$V_{GS(-)} < -10V$ $V_{GS(+)} \geq -10V$	-	50 100	kHz

Note 12. The value of external gate resistance should be considered the surge voltage not to exceed the rating voltage in the worst system condition.

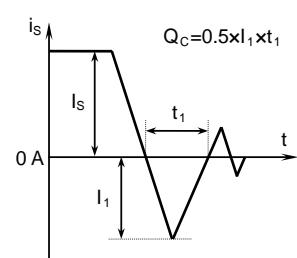
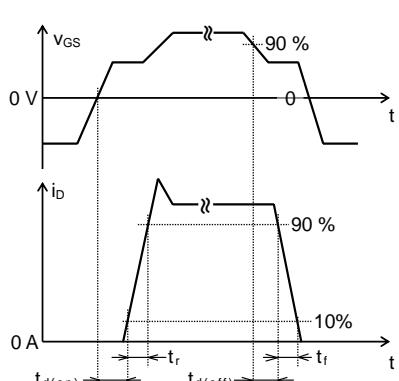
CHIP LOCATION (Top view)Dimension in mm, tolerance: ± 1 mm

Tr1,Tr2: SiC-MOSFET, Di1,Di2: SiC-SBD, Th: NTC thermistor

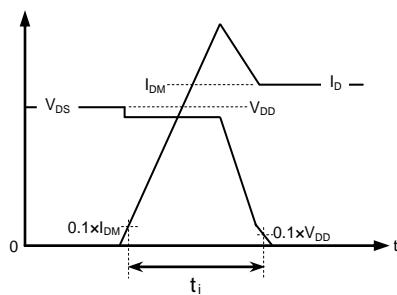
TEST CIRCUIT AND WAVEFORMS



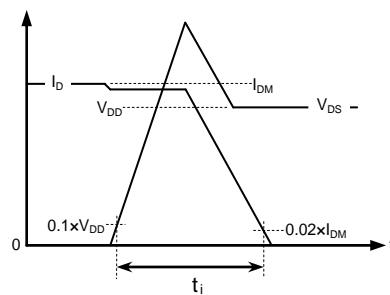
Switching characteristics test circuit and waveforms(x: a or b)



QC test waveform



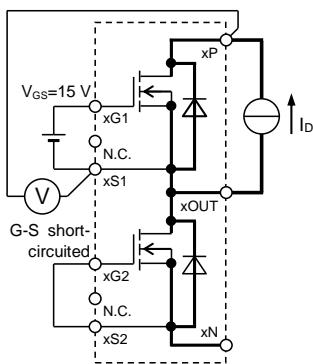
MOSFET Turn-on switching energy



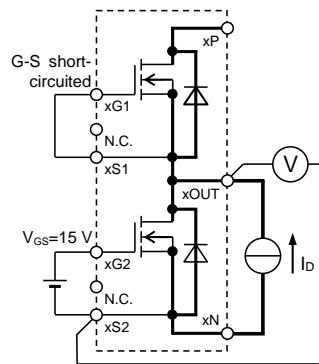
MOSFET Turn-off switching energy

Turn-on / Turn-off switching energy test waveforms (Integral time instruction drawing)

TEST CIRCUIT

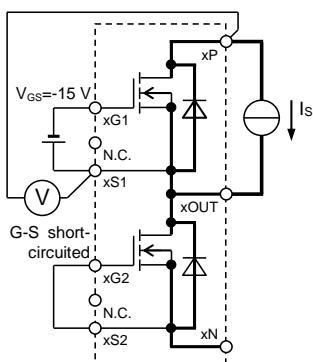


Tr1

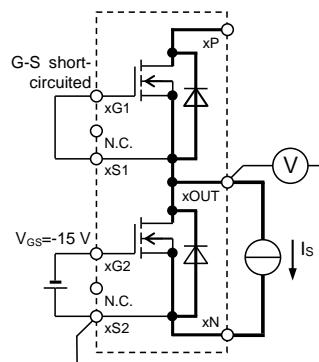


Tr2

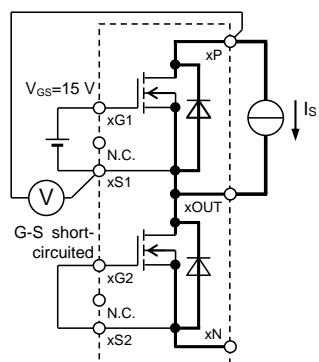
$V_{DS(on)}$ test circuit (x: a or b)



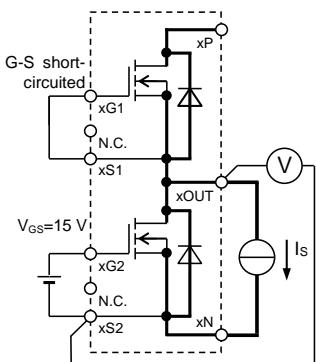
Di1



Di2



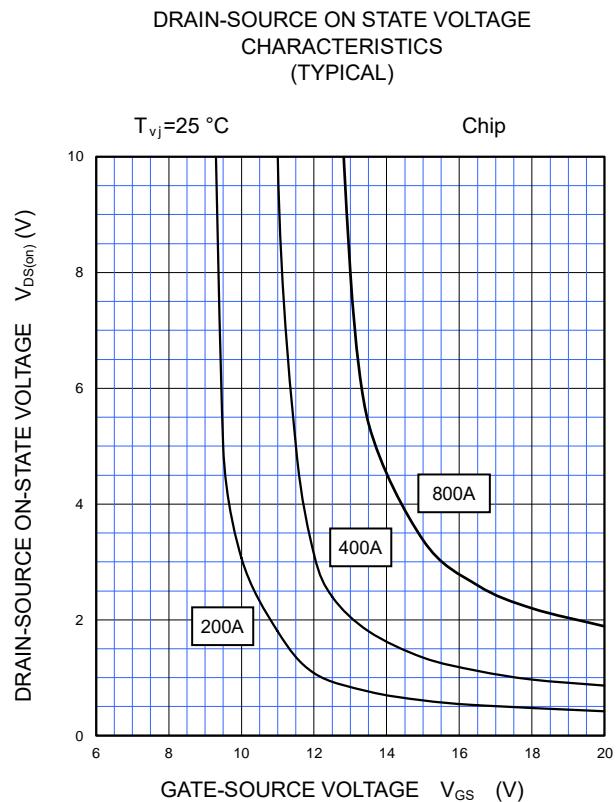
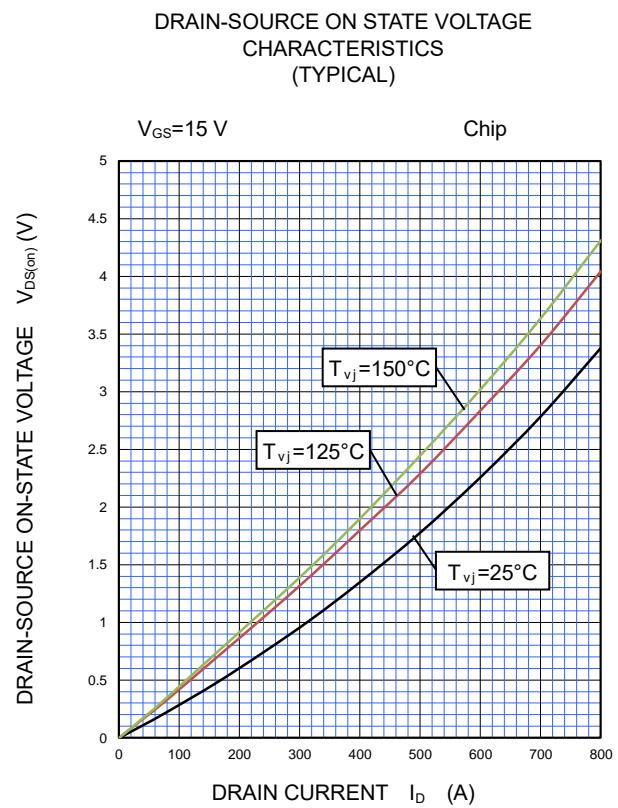
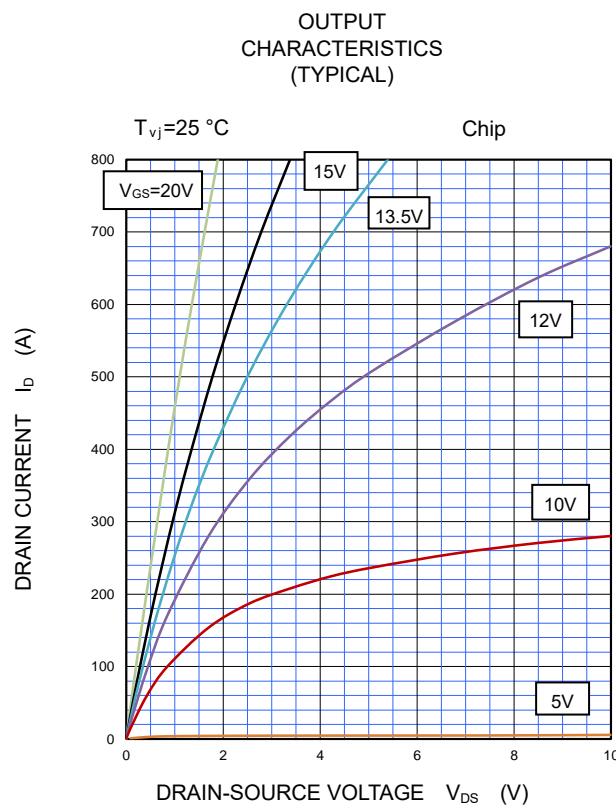
Tr1&Di1



Tr2&Di2

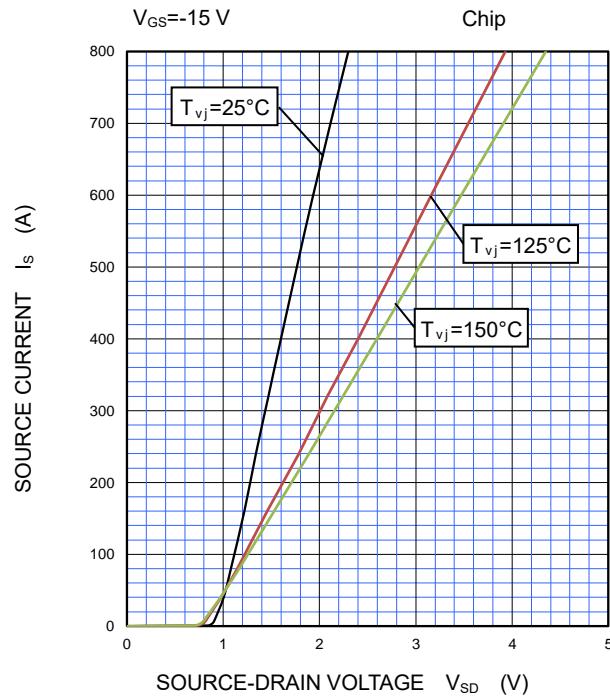
V_{SD} test circuit, $V_{GS}=15V$ (x: a or b)

PERFORMANCE CURVES

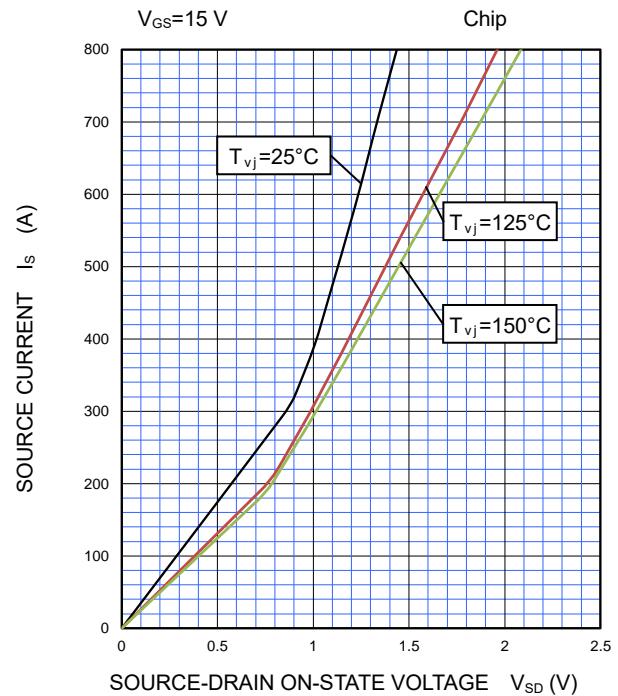


PERFORMANCE CURVES

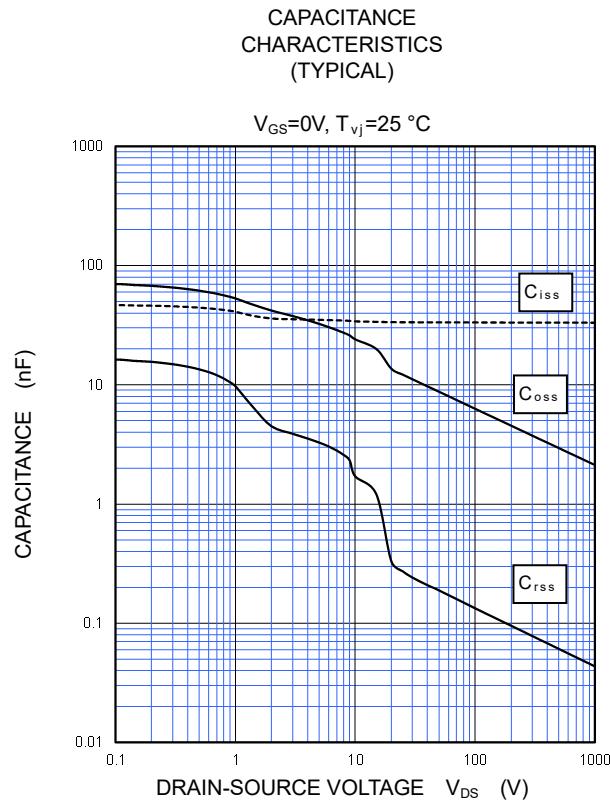
FREE WHEELING DIODE
FORWARD CHARACTERISTICS
(TYPICAL)



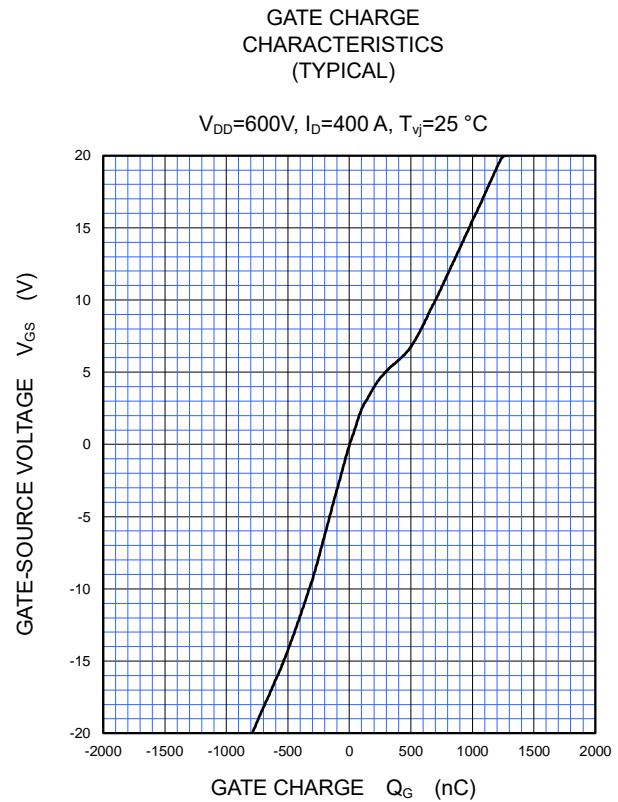
SOURCE-DRAIN ON STATE VOLTAGE
CHARACTERISTICS
(TYPICAL)



CAPACITANCE
CHARACTERISTICS
(TYPICAL)



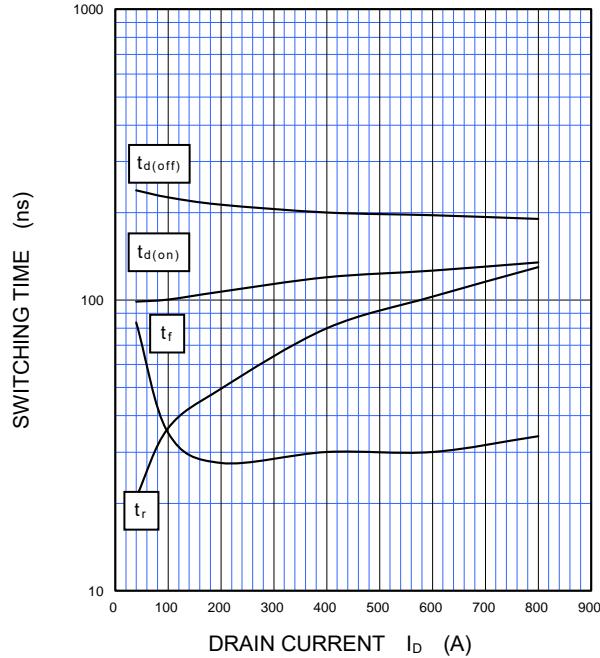
GATE CHARGE
CHARACTERISTICS
(TYPICAL)



PERFORMANCE CURVES

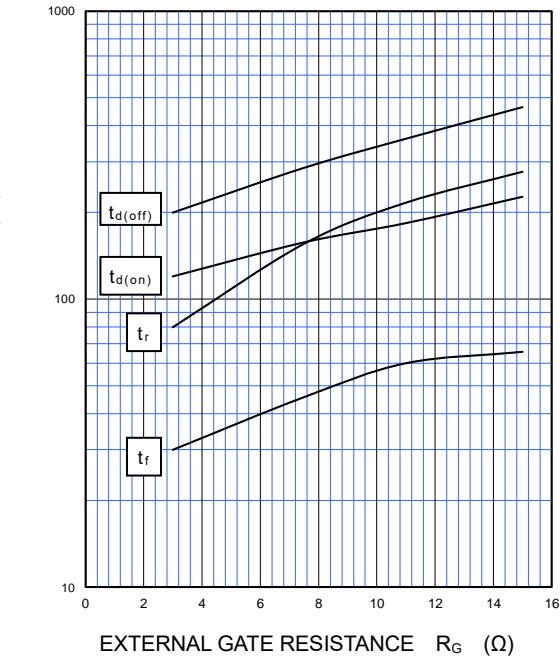
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{DD}=600$ V, $V_{GS}=\pm 15$ V, $R_G=3.0\Omega$, $L_{s_ext}=25nH$
 $T_{vj}=150$ °C, INDUCTIVE LOAD



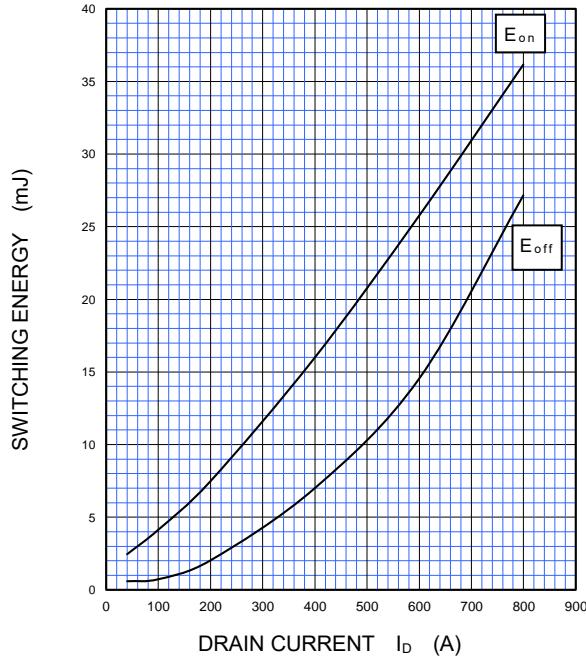
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{DD}=600$ V, $V_{GS}=\pm 15$ V, $I_D=400$ A, $L_{s_ext}=25nH$
 $T_{vj}=150$ °C, INDUCTIVE LOAD



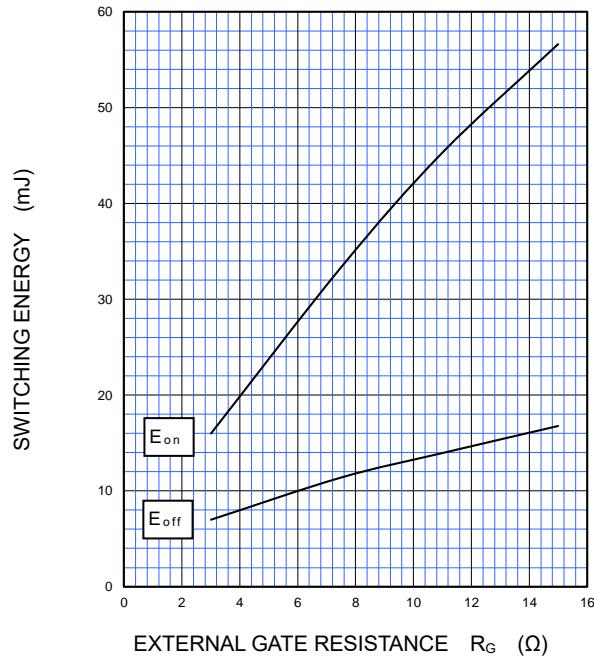
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

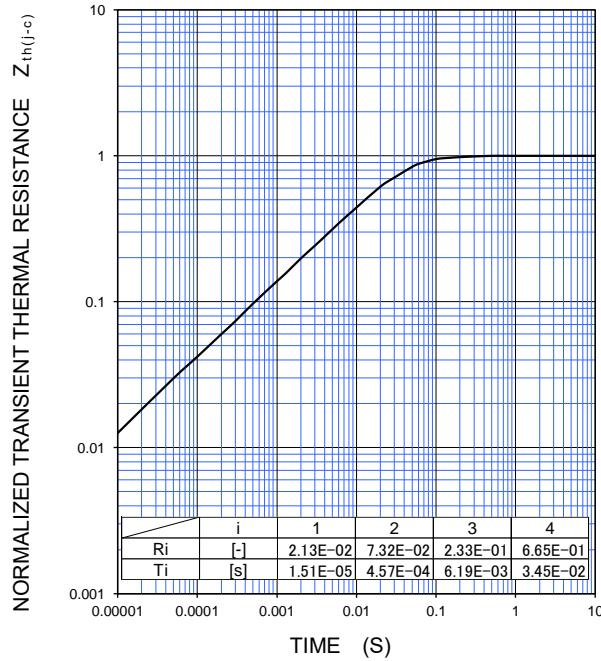
$V_{DD}=600$ V, $V_{GS}=\pm 15$ V, $R_G=3.0\Omega$, $T_{vj}=150$ °C, $L_{s_ext}=25nH$
INDUCTIVE LOAD, PER PULSE



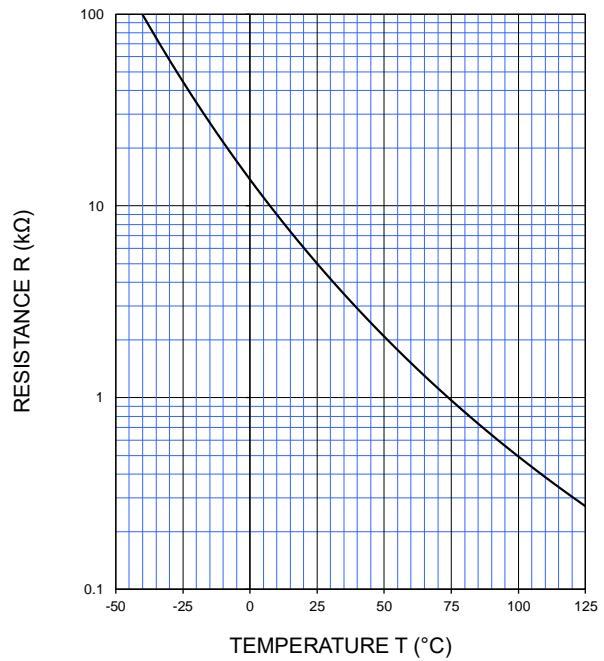
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{DD}=600$ V, $V_{GS}=\pm 15$ V, $I_D=400$ A, $T_{vj}=150$ °C, $L_{s_ext}=25nH$
INDUCTIVE LOAD, PER PULSE



PERFORMANCE CURVESTRANSIENT THERMAL IMPEDANCE
CHARACTERISTICS
(MAXIMUM)Single pulse, $T_C=25\text{ }^\circ\text{C}$
 $R_{th(j-c)Q}=96\text{K/kW}$, $R_{th(j-c)D}=126\text{K/kW}$ 

NTC thermistor part

TEMPERATURE
CHARACTERISTICS
(TYPICAL)

Note: The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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